



2831

#3
JP
11/8/01
Election

TECHNOLOGY CENTER 2000

In re Application of: Tan, Aik Chong et al.
Serial No.: 09/736,462
Filing Date: December 15, 2000
Group Art Unit: 2831
Examiner: Hung V. Ngo
Title: BUMP CHIP LEADFRAME AND PACKAGE

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH
THE UNITED STATES POSTAL SERVICE AS FIRST CLASS MAIL IN AN
ENVELOPE ADDRESSED TO:

COMMISSIONER OF PATENTS AND TRADEMARKS

WASHINGTON, D.C. 20231, ON:

OCTOBER 31, 2001

Date of Deposit

SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC

Name of Assignee

Lysia Mchamara

SIGNATURE

10/31/01

DATE

Honorable Commissioner of Patents and Trademarks,
Washington, D.C. 20231

SIR:

ELECTION

In response to the Office Action mailed October 19, 2001,
Applicants respectfully request the election of the Group I
claims, which include claims 1-9 pursuant to 37 CFR 1.142(a)
without traverse. Group II include claims 10-16, which are
drawn to a lead frame, classified in class 257, subclass 666.